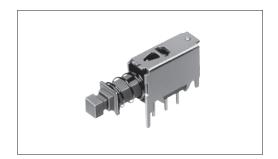
2.5mm-travel Compact-sized Horizontal Type

Lever height 4.7mm, small sized horizontal type







■ Typical Specifications

Ite	ms	Specifications	
Rating (max.)/(min.) (Resistive load)		0.2A 30V DC / 50 μA 3V DC	
Contact resistand (Initial/After opera	t resistance After operating life) 20mΩ max. / 40		
Operating force	1-pole	2.3±1N	
	2-pole	3.3±1N	
Operating life	Without load	10,000 cycles	
Operating life	With load	10,000 cycles (0.2A 30V DC)	

Product Line

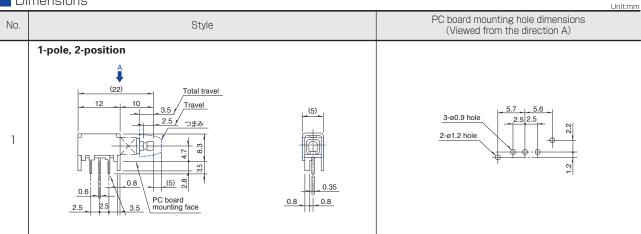
Changeover timing	Travel (mm)	Total travel (mm)	Mounting method	Poles	Operation	Terminal type	Minimum ord Japan	er unit (pcs.) Export	Product No.	Drawing No.							
Non shorting 2.5			Latching			SPPJ310500	,										
	0.5	2.5 3.5 PC	3.5 PC board	'	Momentary	For	100	4.500	SPPJ311500	'							
	2.5			2	i o board	PG board	PG DOdiu	PC Doard	r C Dodiu	i o board	0	Latching	PC board	100	4,500	SPPJ320600	2
					2	Momentary				SPPJ322300							

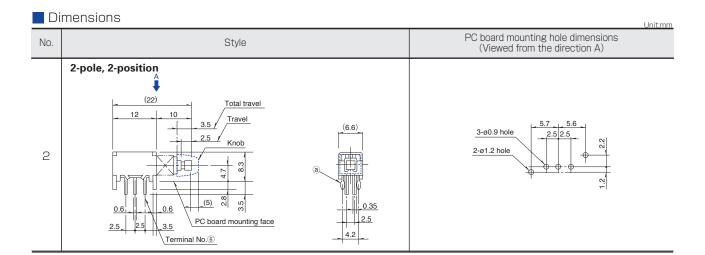
Packing Specifications

Bulk

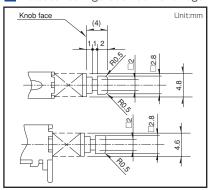
Number of pa	ckages (pcs.)	Export package measurements
1 case / Japan	1 case / export packing	(mm)
900	4,500	400×270×290

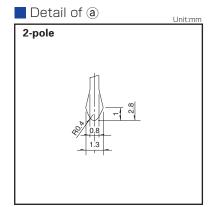
Dimensions

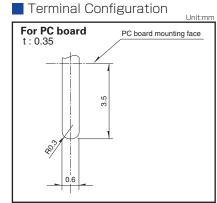




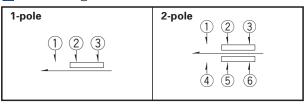
Actuator Configuration at Front Edge

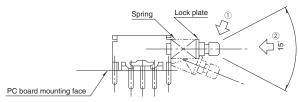






■ Circuit Diagram (Viewed from Direction A)





Note

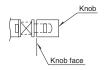
The SPPJ3 series should be operated in arrow 2 direction as shown in the following figure and applied within an angle of 15° based from the center. If excessive force is applied to the lever from arrow ① direction, it may fall down as illustrated and cause malfunctions.

Attached Parts

Attached Parts		Unit:mm
Knob outline drawing	Model	
4.6	Color:Black	UJ206022

Notes

- 1. Other knob varieties are also available. Please inquire.
- 2. We recommend the use of adhesive to secure the knob when mounting onto switches.





	Corioo				Horizontal			
,	Series		SPPJ3	SPPJ2	SPUJ*	SPUN	SPUN medium current*	
ı	Photo							
W		5 or 6.6	7.2	7.5		10		
Dimensions (mm)		D	1	2	15.2 22.7	24 36		
		Н	8.3 9.6		8.8	13		
Tra	vel (mm)		2	.5	2		2.5	
Total	travel (m	m)	3	.5	3		3.5	
Numb	er of pol	es	1 2	2		2 4		
	erating rature rai	nge	–40°C to +85°C		-10°C to	o +60℃		
Autor	motive us	se	•	•	_	_	_	
Lit	Life cycle		*3	*3	★ 3			
Rating (max.) (Resistive load) 0.2A 30V DC 0.1A 30V DC			OV DC	1A 25V DC				
Rati (Resi	Rating (min.) (Resistive load) 50 \(\mu \) A 3V DC				1A 25V DC			
Durahilitu	Operating life without load		10	D,000 cycles 40mΩ ma	эх.	30,000 cycles 40mΩ max.	10,000 cycles 40mΩ max.	
Durability		ife with load ated load)		10,000 cycles 40mΩ max. 5,000 cycles 40mΩ max.				
		contact tance			20mΩ max.			
Electrical performance		ation tance		100MΩ min. 500V DC				
	Voltag	e proof			500V AC for 1minute			
		ninal ngth		5N for 1minute				
Mechanical performance	Actuato	Operating direction	50N	30N		50N		
	strength	Pulling direction	_	_		50N		
Cold			-40°C 96h -20°C 96h					
Environmental performance	Dry heat		85°C 96h					
	Damp) heat		40°C, 90 to 95%RH 96h				
	Page		116	118	120 122			

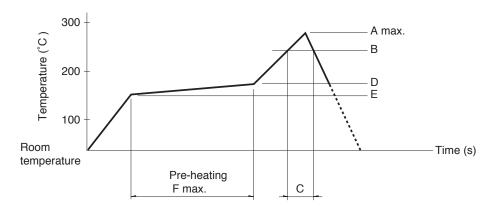
Notes

- 1. * The operating temperature range for automotive applications can be raised upon request. Please contact us for details.
- 2. Indicates applicability to all products in the series.

Push Switches Soldering Conditions

Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.
- 3. Temperature profile



Series (Reflow type)	A (℃) 3s max.	B (℃)	C (s)	D (°C)	E (℃)	F(s)
SPEG						
SPEJ	260	230	40	180	150	120
SPEF	200	200	40	100	150	120
SPEH						

Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time	
SPPJ3, SPPJ2, SPUN, SPPH4, SPPH1	350±10℃	3+1/0s	
SPED2, SPED4	350±10℃	3±0.5s	
SPEJ	350±10°C	4s max.	
SPEG, SPEF	350±5℃	3s max.	
SPEH, SPPH2	350°C max.	3s max.	
SPUJ	300±10°C	3+1/0s	

Reference for Dip Soldering (For PC board terminal types)

Series	Ite	ms	Dip soldering		
Jelles	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion	
SPPJ3	100℃ max.	60s max.	260±5℃	5±1s	
SPUN	100℃ max.	60s max.	260±5℃	10±1s	
SPUJ, SPPH2, SPPH4	_		260±5℃	5±1s	
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_		260±5℃	10±1s	

